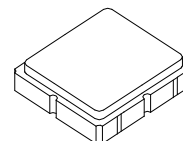


RFM products are now
Murata products.

SF2360D

864 MHz SAW Filter



SM3838-8 Case

- *Designed for 802.11 Applications*
- *Hermetically sealed Surface Mount package*
- *Complies with Directive 2002/95/EC (RoHS)*



Absolute Maximum Ratings

Rating	Value	Units
Maximum Input Power	+5	dBm
DC Voltage Between Terminals	3	VDC
Storage Temperature	-10 to +60	°C
Operating Temperature	-40 to +85	°C
Suitable for lead-free soldering - Max Soldering Profile	260°C for 30 s	

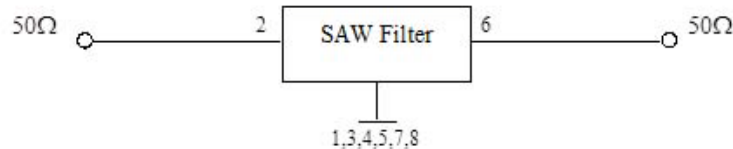
Electrical Characteristics

Characteristic	Sym	Notes	Minimum	Typical	Maximum	Units
Center Frequency	f_c			864		MHz
Insertion Loss 862 to 866 MHz	IL			2.4	3.5	dB
Amplitude Ripple 862 to 866				0.3	1.3	dB
Attenuation (reference level from 0 dB)						
820 to 823 MHz			38	44		dB
841 to 844 MHz			35	42		
905 to 908 MHz			40	47		
Temperature Coefficient of Frequency				-36		ppm/k
Source Impedance	Z_S			50		Ω
Load Impedance	Z_L			50		Ω
Footprint Size: 3.8 X 3.8	SM3838-8					
Lid Symbolization (Y=Year, WW=week, S=shift)	B24// YWWS					

Electrical Connections

Connection	Terminals
Input	2
Output	6
Ground	1, 3, 4, 5, 7, 8

HP Network analyzer

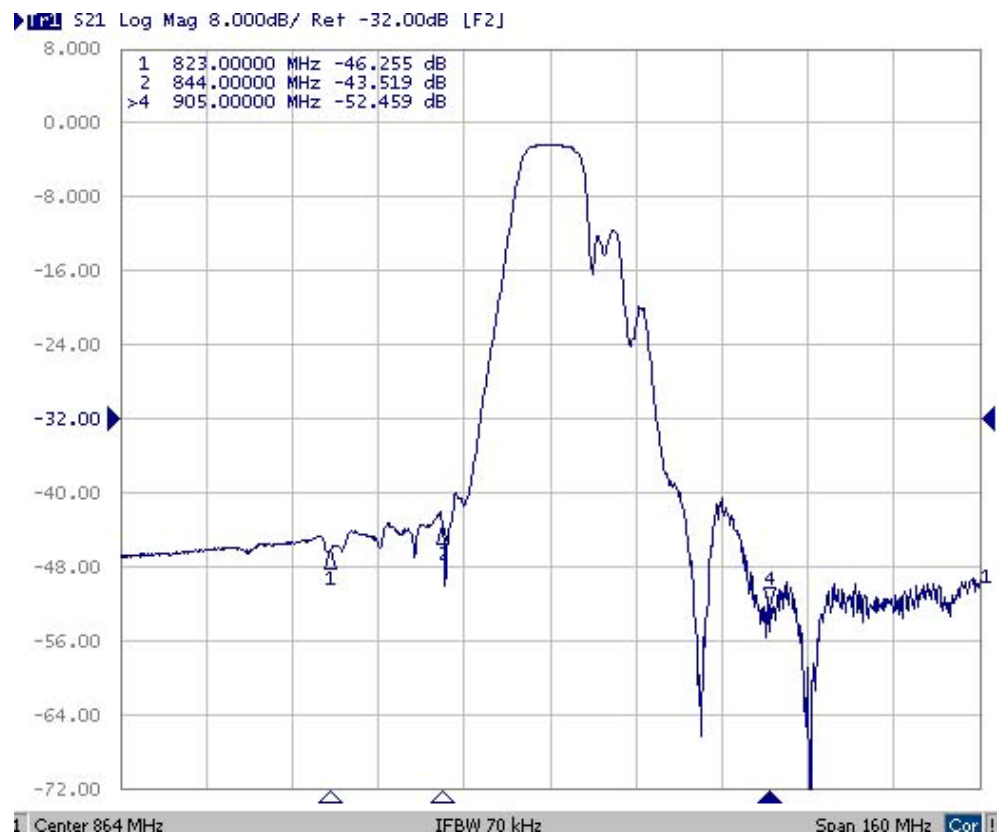
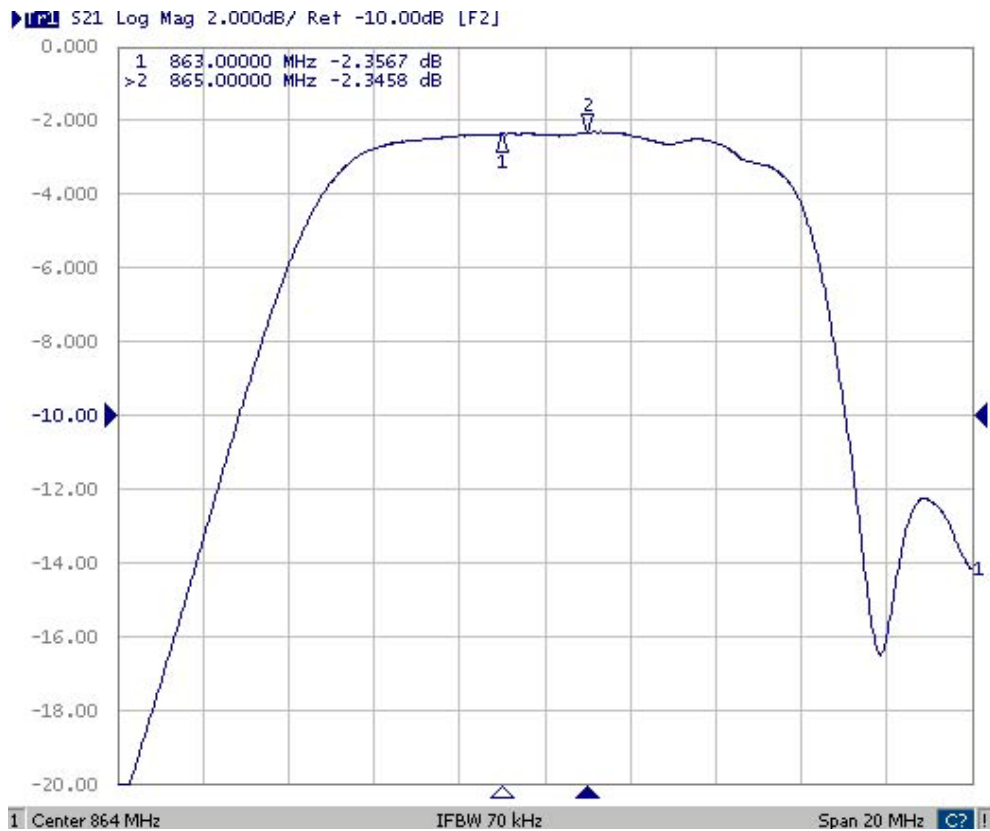


CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.

NOTES:

1. All specifications apply over the operating temperature range with filter soldered to the specified demonstration board unless noted otherwise.
2. Ultimate rejection is dependent on PCB layout.
3. Specifications subject to change without notice.
4. Electrostatic Sensitive Device. Observe precautions for handling.
5. US and international patents may apply.
6. Murata, stylized Murata logo, and Murata N.A., Inc. are registered trademarks of Murata Manufacturing Co., Ltd.

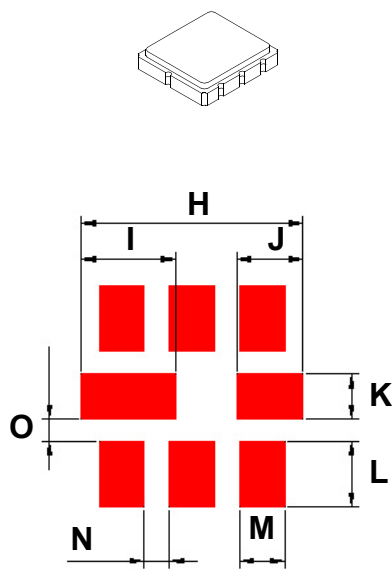
Transfer Function



SM3838-8 Case

8-Terminal Ceramic Surface-Mount Case

3.8 X 3.8 mm Nominal Footprint



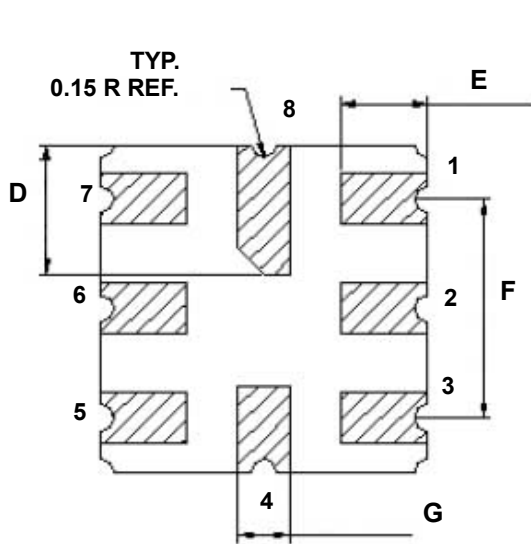
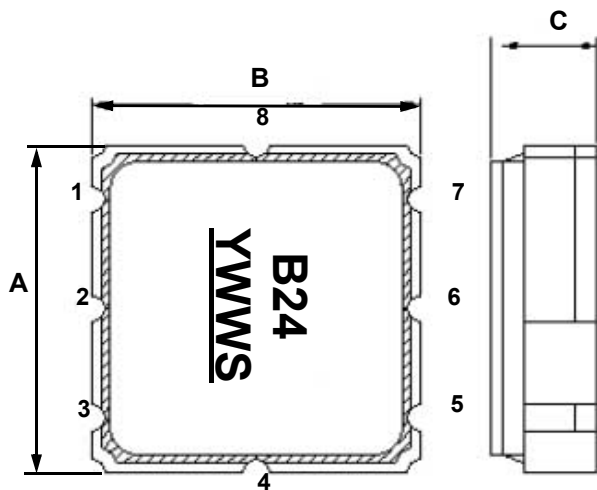
PCB Footprint

Case Dimensions						
Dimension	mm			Inches		
	Min	Nom	Max	Min	Nom	Max
A	3.65	3.80	3.95	0.143	0.149	0.155
B	3.65	3.80	3.95	0.143	0.149	0.155
C		1.40		0.055	0.055	
D		1.50			0.059	
E		1.00			0.039	
F		2.54			0.100	
G		0.60			0.023	
H		4.01			0.15	
I		1.70			0.066	
J		1.19			0.046	
K		0.81			0.031	
L		1.19			0.046	
M		0.81			0.003	
N		0.46			0.018	
O		0.41			0.016	

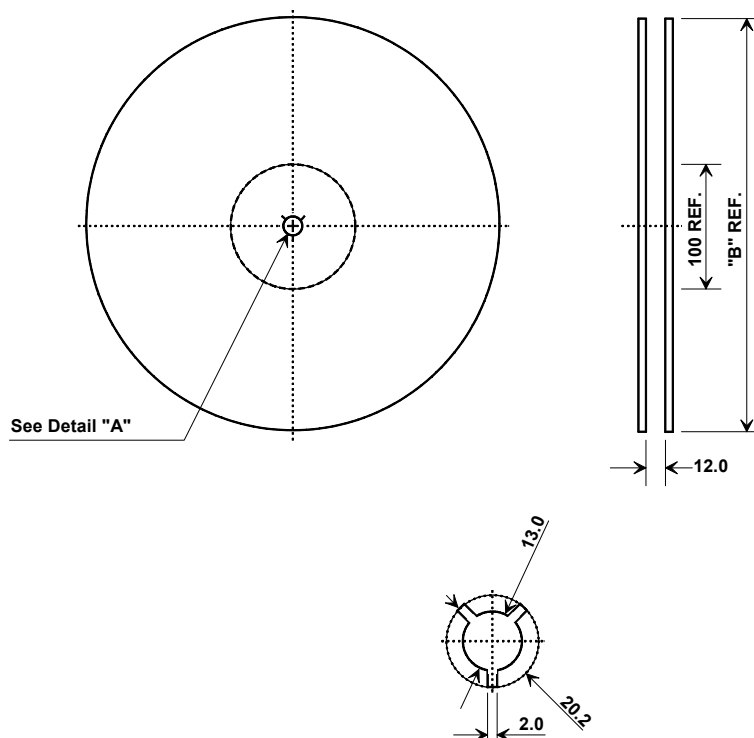
Materials	
Solder Pad Termination	Au plating 30 - 60 ulnches (76.2-152 uM) over 80-200 ulnches (203-508 uM) Ni.
Lid	Fe-Ni-Co Alloy Electroless Nickel Plate (8-11% Phosphorus) 100-200 ulnches Thick
Body	Al ₂ O ₃ Ceramic
Pb Free	

TOP VIEW

BOTTOM VIEW



Tape and Reel Specifications



“B “ Nominal Size		Quantity Per Reel
Inches	millimeters	
7	178	500
13	330	3000

COMPONENT ORIENTATION and DIMENSIONS

Carrier Tape Dimensions	
Ao	4.25 mm
Bo	4.25 mm
Ko	1.30 mm
Pitch	8.0 mm
W	12.0 mm

